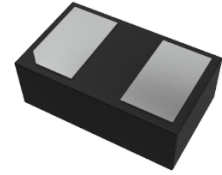


Features

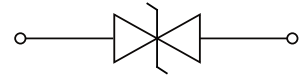
- Low capacitance: 15pF(Typ.)
- Reverse Working Voltage: 5V
- Bi-directional protection
- DFN0603 surface mount package
- IEC 61000-4-2 (ESD Air): ±30kV
- IEC 61000-4-2 (ESD Contact): ±30kV
- IEC 61000-4-5 (Lightning 8/20μs): 8A

DFN0603



Applications

- Smart Phone and Tablet PC
- TV and Set Top Box
- Wearable Devices
- Digital cameras
- PADs

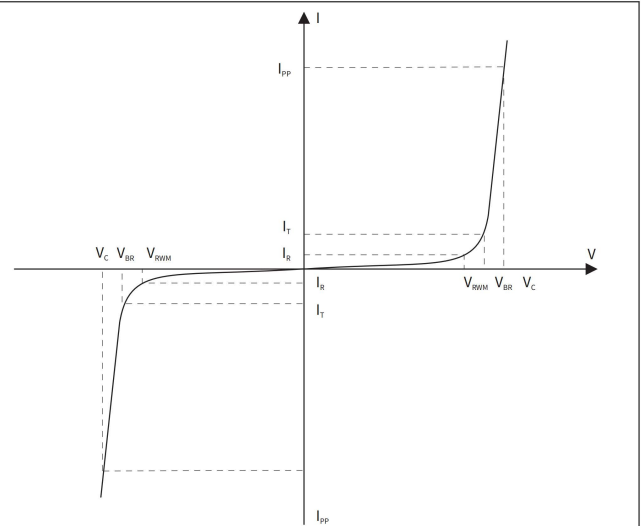


Maximum Ratings (Ta=25°C Unless otherwise specified)

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
V _{ESD}	Electrostatic Discharge Voltage	ESD per IEC 61000-4-2(Air)	±30	KV
		ESD per IEC 61000-4-2(Contact)	±30	KV
P _{PP}	Peak Pulse Power	tp = 8/20 μs	80	W
I _{PP}	Rated Peak Pulse Current	tp = 8/20 μs	7	A
T _J	Operating JunctionTemperature Range	—	-55 to +125	°C
T _{stg}	Storage Temperature Range	—	-55 to +150	°C

Electrical Parameter

SYMBOL	PARAMETER
V _C	Clamping Voltage @ I _{PP}
V _{BR}	Breakdown Voltage @ I _T
I _{PP}	Peak Pulse Current
I _T	Test Current
I _R	Reverse Leakage Current @ V _{RWM}
V _{RWM}	Peak Reverse Working Voltage
P _{PP}	Peak Pulse Power Dissipation
C _J	Junction Capacitance @ V _R =0V,f=1MHz



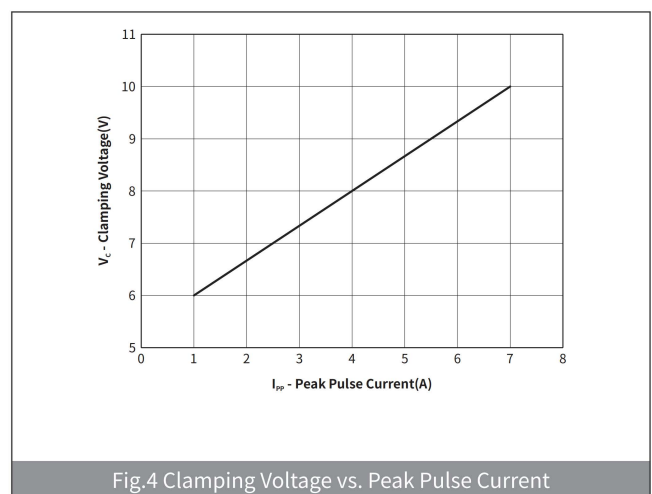
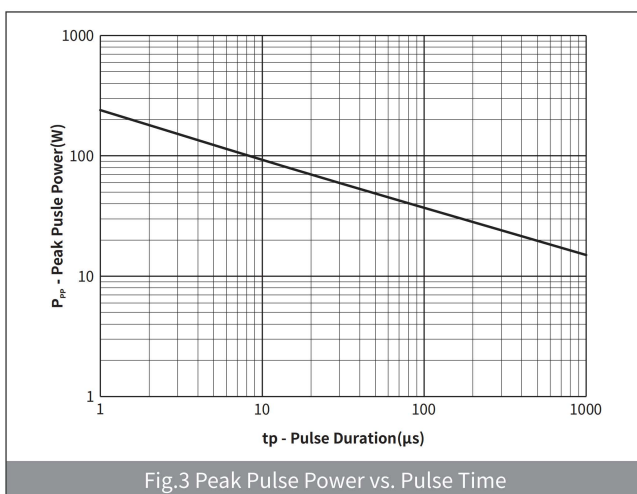
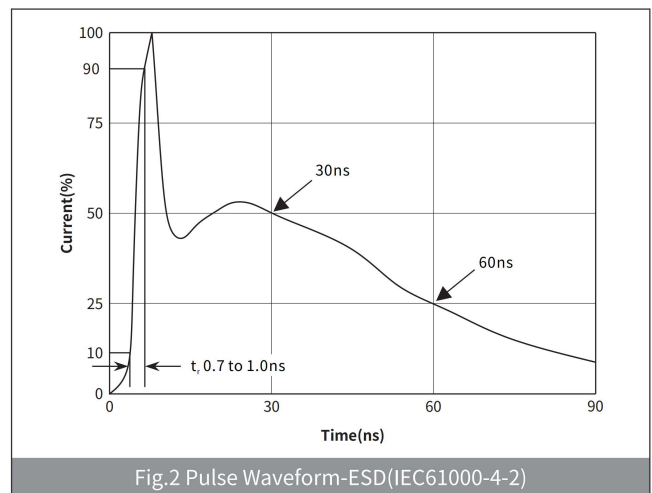
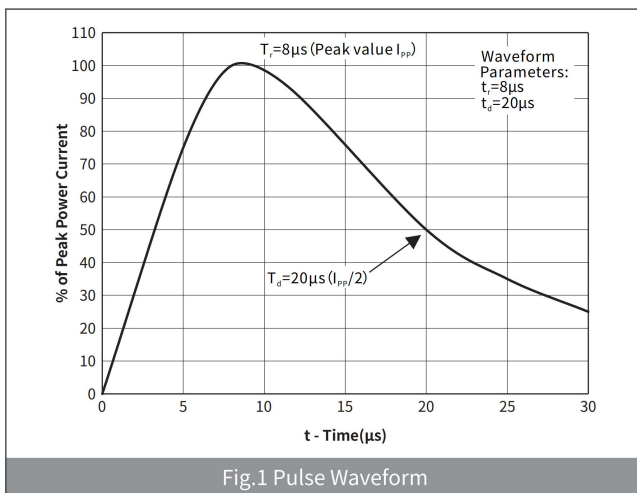
Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Peak Reverse Working Voltage	V_{RWM}	$T_A=25^\circ\text{C}$	—	—	5.0	V
Breakdown Voltage	V_{BR}	$I_T=1\text{mA}; T_A=25^\circ\text{C}$	5.6	—	8.4	V
Reverse Leakage Current	I_R	$V_{RWM}=5.0\text{V}; T_A=25^\circ\text{C}$	—	—	0.1	μA
Clamping Voltage	V_C	$I_{pp}=1.0\text{A}, t_p=8/20\mu\text{s}$	—	—	6.0	V
		$I_{pp}=8.0\text{A}, t_p=8/20\mu\text{s}$	—	—	10.0	V
Junction Capacitance	C_J	$V_R=0\text{V}, f=1\text{MHz}$	—	15	20	pF

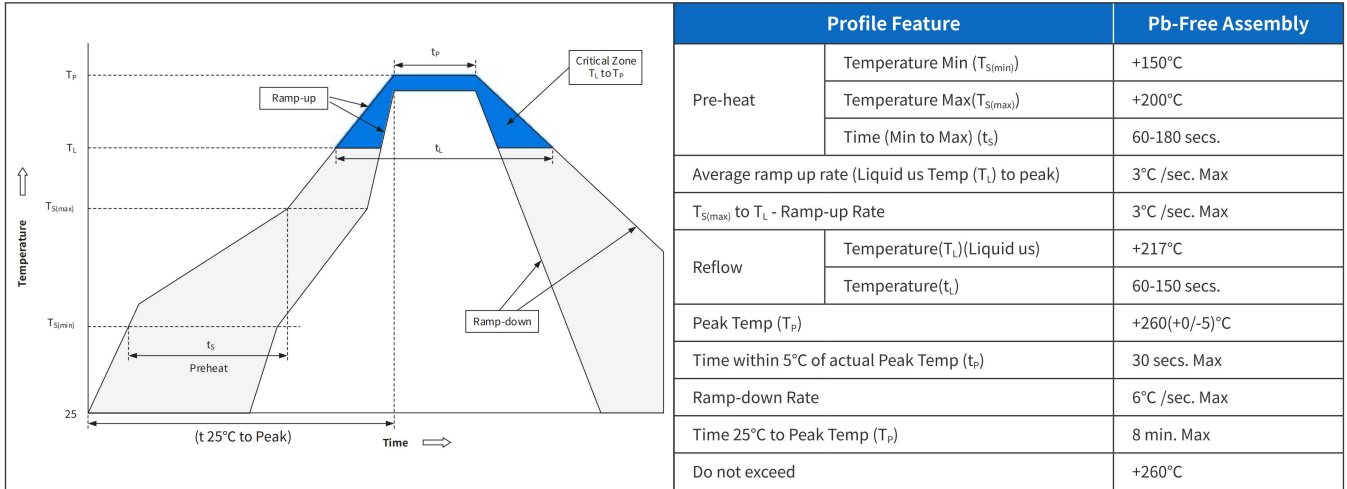
Ordering Information

PREFERRED P/N	PACKAGE	SIZE(mm)	DELIVERY MODE	MPQ(PCS)
H5VL06B	DFN0603	0.60×0.30×0.30	7" REEL	15,000

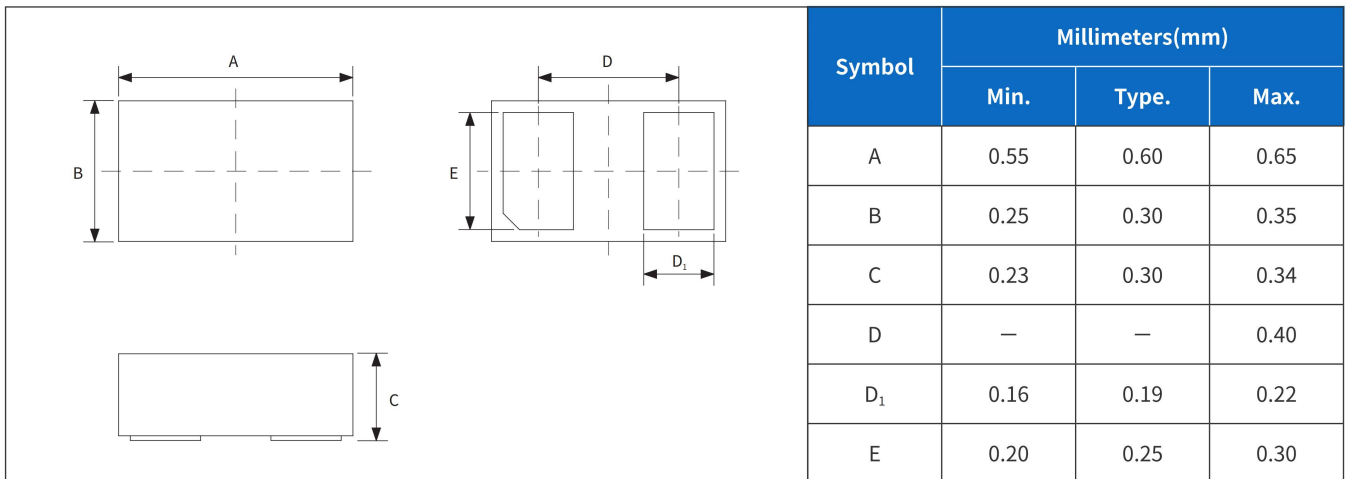
Ratings And Characteristics Curves (Ta=25°C Unless otherwise specified)



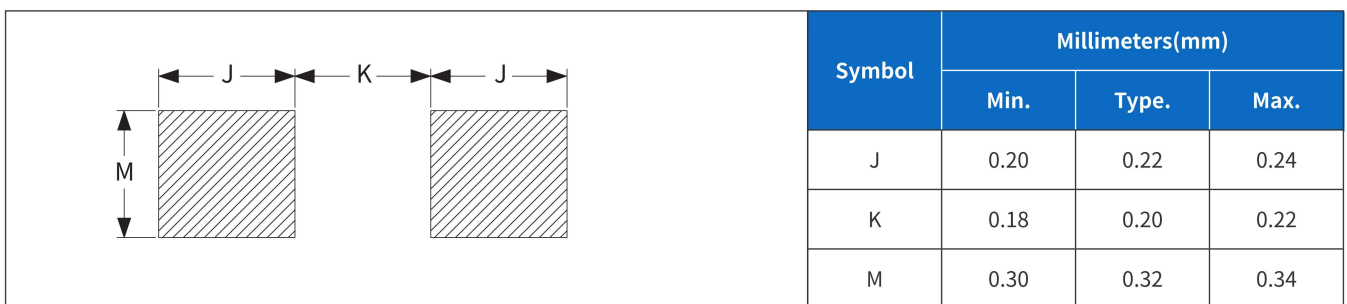
Recommended Soldering Conditions



Package Outline Dimensions (DFN0603)



Suggested Pad Layout



Note:

This soldering footprint is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.